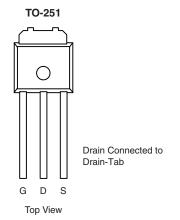


SM1F12NSUB-VB Datasheet N-Channel 200-V (D-S) MOSFET

PRODUCT SUMMARY					
V _{(BR)DSS} (V)	$R_{DS(on)}(\Omega)$	I _D (A)	Q _g (Typ.)		
200	0.038 at V _{GS} = 15 V	40	57		
	0.043 at V _{GS} = 10 V	35	37		



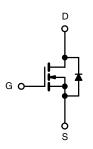
FEATURES

- Trench Power MOSFETS
- 175 °C Junction Temperature
- 100 % R_g and UIS Tested



APPLICATIONS

- Power Supply
- · Lighting Systems



N-Channel MOSFET

ABSOLUTE MAXIMUM RATINGS	T _A = 25 °C, unless oth	erwise noted			
Parameter	Symbol	Limit	Unit		
Drain-Source Voltage	V _{DS}	200	V		
Gate-Source Voltage	V _{GS}	± 25	7 v		
Continuous Drain Current (T _{.I} = 175 °C)	T _C = 25 °C	1-	40		
Continuous Diain Current (1) = 175 C)	T _C = 100 °C	I _D	26		
Pulsed Drain Current	I _{DM}	150	Α		
Single Pulse Avalanche Current	L = 0.1 mH	I _{AS}	20		
Single Pulse Avalanche Energy ^a	L = 0.1 IIII1	E _{AS}	20	mJ	
Maximum Power Dissipation ^a	T _C = 25 °C	D	146 ^b	W	
	T _A = 25 °C ^c	$ P_{D}$	3.12		
Operating Junction and Storage Temperature Ra	T _J , T _{stg}	- 55 to 175	°C		

THERMAL RESISTANCE RATINGS					
Parameter	Symbol	Limit	Unit		
Junction-to-Ambient (PCB Mount) ^c	R _{thJA}	40	°C/W		
Junction-to-Case (Drain)	R _{thJC}	0.75	C/VV		

Notes:

- a. Duty cycle \leq 1 %.
- b. See SOA curve for voltage derating.
- c. When Mounted on 1" square PCB (FR-4 material).

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Parameter	Symbol	Test Conditions	Min.	Тур.	Max.	Unit	
Static							
Drain-Source Breakdown Voltage	V _{(BR)DSS}	$V_{GS} = 0 \text{ V, } I_D = 250 \mu\text{A}$ 200				V	
Gate Threshold Voltage	V _{GS(th)}	$V_{DS} = V_{GS}, I_D = 250 \mu A$	2.5		4.5	, v	
Gate-Body Leakage	,	$V_{DS} = 0 \text{ V}, V_{GS} = \pm 20 \text{ V}$			± 100	nA	
	I _{GSS}	$V_{DS} = 0 \text{ V}, V_{GS} = \pm 25 \text{ V}$			± 300		
		V _{DS} = 200 V, V _{GS} = 0 V			1		
Zero Gate Voltage Drain Current	I _{DSS}	$V_{DS} = 200 \text{ V}, V_{GS} = 0 \text{ V}, T_{J} = 100 ^{\circ}\text{C}$			25	μΑ	
-		$V_{DS} = 200 \text{ V}, V_{GS} = 0 \text{ V}, T_{J} = 150 ^{\circ}\text{C}$			250	1 .	
On-State Drain Current ^a	I _{D(on)}	$V_{DS} \ge 10 \text{ V}, V_{GS} = 10 \text{ V}$	40			Α	
		V _{GS} = 10 V, I _D = 20 A		0.038			
	_D	V _{GS} = 15 V, I _D = 20 A		0.043		Ω	
Drain-Source On-State Resistance ^a	R _{DS(on)}	V _{GS} = 10 V, I _D = 20 A, T _J = 100 °C		0.088			
		V _{GS} = 10 V, I _D = 20 A, T _J = 150 °C		0.120			
Forward Transconductance ^a	9 _{fs}	V _{DS} = 15 V, I _D = 20 A	25			S	
Dynamie th	•			•			
Input Capacitance	C _{iss}			3100			
Output Capacitance	C _{oss}	V _{GS} = 0 V, V _{DS} = 25 V, f = 1 MHz		300		pF	
Reverse Transfer Capacitance	C _{rss}			135			
Total Cata Charge ^C	Qg	$V_{DS} = 100 \text{ V}, V_{GS} = 15 \text{ V}, I_D = 50 \text{ A}$		85	127		
Total Gate Charge ^c	∀ g			57	85	nC	
Gate-Source Charge ^c	Q_{gs}	$V_{DS} = 100 \text{ V}, V_{GS} = 10 \text{ V}, I_D = 50 \text{ A}$		14		nC	
Gate-Drain Charge ^c	Q_{gd}			20			
Gate Resistance	R_{g}	f = 1 MHz		1.2	1.8	Ω	
Turn-On Delay Time ^c	t _{d(on)}			16	25		
Rise Time ^c	t _r	V_{DD} = 100 V, R_L = 2 Ω		170	260	20	
Turn-Off Delay Time ^c	t _{d(off)}	$I_D \cong 50 \text{ A}, V_{GEN} = 10 \text{ V}, R_g = 1 \Omega$		27	42	ns	
Fall Time ^c	t _f			9	18	<u> </u>	
Source-Drain Diorder Battings Sannic Chla	Tabiskipsas s						
Continuous Current	Is				36		
Pulsed Current	I _{SM}				80	Α	
Forward Voltage ^a	V _{SD}	I _F = 20 A, V _{GS} = 0 V		0.86	1.5	٧	
Reverse Recovery Time	t _{rr}			116	175	ns	
Peak Reverse Recovery Current	I _{RM(REC)}			9	14	Α	
Reverse Recovery Charge	Q _{rr}	$I_F = 40 \text{ A}, \text{ di/dt} = 100 \text{ A/}\mu\text{s}$		0.53	0.8	μC	
Reverse Recovery Fall Time	t _a			84		•	
Reverse Recovery Rise Time	t _b			32		nS	

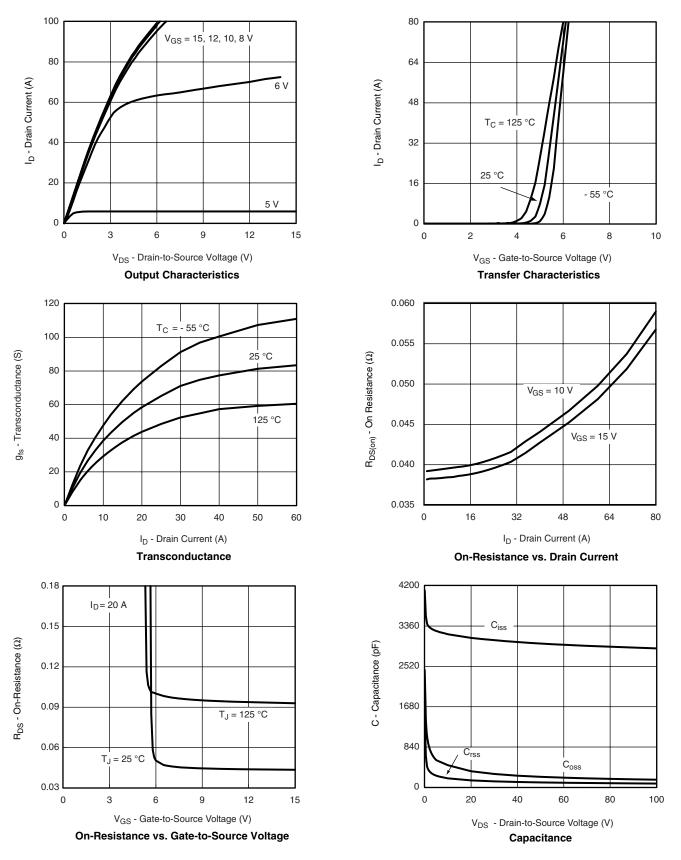
Notes:

- a. Pulse test; pulse width $\leq 300~\mu s,$ duty cycle $\leq 2~\%.$
- b. Guaranteed by design, not subject to production testing.
- c. Independent of operating temperature.

Stresses beyond those listed under "Absolute Maximum Ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated in the operational sections of the specifications is not implied. Exposure to absolute maximum rating conditions for extended periods may affect device reliability.

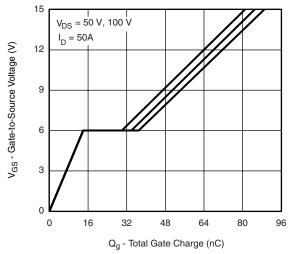


TYPICAL CHARACTERISTICS 25 °C, unless otherwise noted

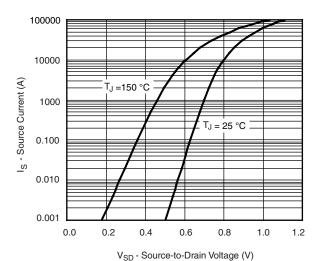




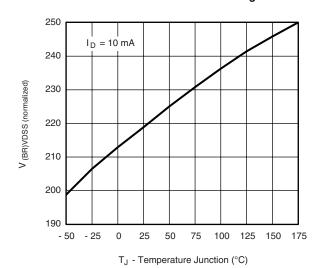
TYPICAL CHARACTERISTICS 25 °C, unless otherwise noted



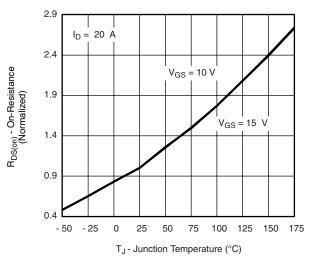




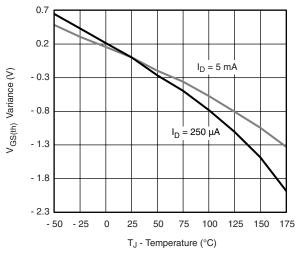
Source-Drain Diode Forward Voltage



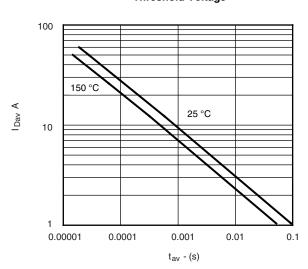
Drain Source Breakdown vs. Junction Temperature



On-Resistance vs. Junction Temperature



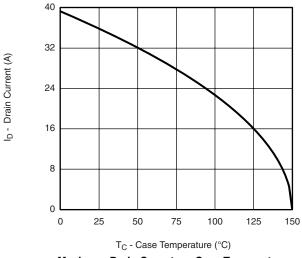
Threshold Voltage

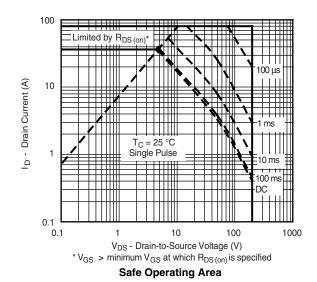


Single Pulse Avalanche Current Capability vs. Time

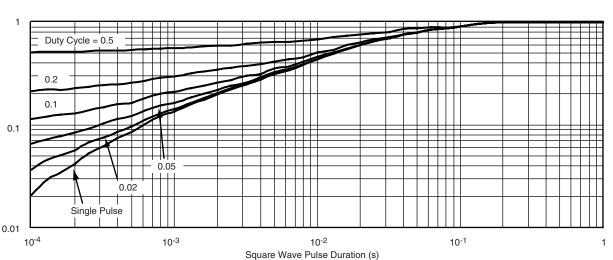


THERMAL RATINGS





Maximum Drain Curent vs. Case Temperature



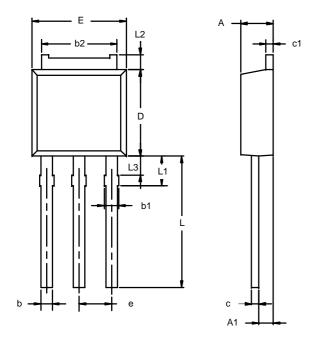
Normalized Thermal Transient Impedance, Junction-to-Case

Normalized Effective Transient Thermal Impedance

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TO-251AA



Noto:	Dimension	1 2 ic for	roforonco	only
mote:	Dimension	L3 IS 101	reference	OHIV.

	IETERS	INC	HES
Min	Max	Min	Max
2.21	2.38	0.087	0.094
0.89	1.14	0.035	0.045
0.71	0.89	0.028	0.035
0.76	1.14	0.030	0.045
5.23	5.43	0.206	0.214
0.46	0.58	0.018	0.023
0.46	0.58	0.018	0.023
5.97	6.22	0.235	0.245
6.48	6.73	0.255	0.265
2.28 BSC		0.090	BSC
3.89	9.53	0.153	0.375
1.91	2.28	0.075	0.090
0.89	1.27	0.035	0.050
1.15	1.52	0.045	0.060
	2.21 0.89 0.71 0.76 5.23 0.46 0.46 5.97 6.48 2.28 3.89 1.91 0.89	2.21 2.38 0.89 1.14 0.71 0.89 0.76 1.14 5.23 5.43 0.46 0.58 0.46 0.58 5.97 6.22 6.48 6.73 2.28 BSC 3.89 9.53 1.91 2.28 0.89 1.27	2.21 2.38 0.087 0.89 1.14 0.035 0.71 0.89 0.028 0.76 1.14 0.030 5.23 5.43 0.206 0.46 0.58 0.018 0.46 0.58 0.018 5.97 6.22 0.235 6.48 6.73 0.255 2.28 BSC 0.090 3.89 9.53 0.153 1.91 2.28 0.075 0.89 1.27 0.035 1.15 1.52 0.045

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